

Features

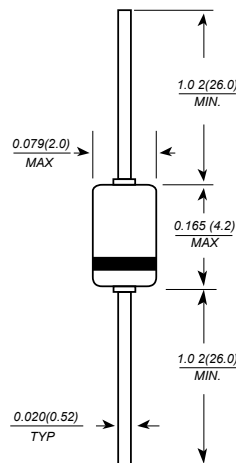
- Metal-to-silicon junction
- High breakdown voltage
- Low turn-on voltage
- Ultrafast switching speed

Mechanical Data

- Case: DO-35, glass case
- Polarity: Color band denotes cathode
- Weight: 0.004 ounces, 0.13 grams



DO-35(GLASS)



Dimensions in millimeters

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbols	Value	Unit
Peak reverse voltage	V_{RRM}	20.0	V
Power dissipation (Infinite Heat Sink)	P_{tot}	430.0	mW
Forward continuous current	I_{FSM}	35.0	mA
Junction and storage temperature range	T_J/T_{STG}	-55 ---+ 150	$^\circ\text{C}$
Maximum lead temperature for soldering during 10S at 4mm from case	T_L	230	$^\circ\text{C}$

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbols	Min.	Typ.	Max.	Unit
Reverse breakdown voltage @ $I_R=10\mu\text{A}$	V_R	20.0			V
Leakage current @ $V_R=16\text{V}$	I_R			150	nA
Forward voltage drop @ $I_F=1\text{mA}$	V_F			0.41	V
Test pulse: $t_p \leq 300\mu\text{s}$ $\delta < 2\%$ $I_F=35\text{mA}$				1.0	
Junction capacitance @ $V_R=0\text{V}, f=1\text{MHz}$	C_J			2	pF
Thermal resistance	$R_{\theta JA}$			400	KW

FIG.1 – TYPICAL CURRENT VERSUS FORWARD VOLTAGE AT DIFFERENT TEMPERATURES (TYPICAL VALUES)

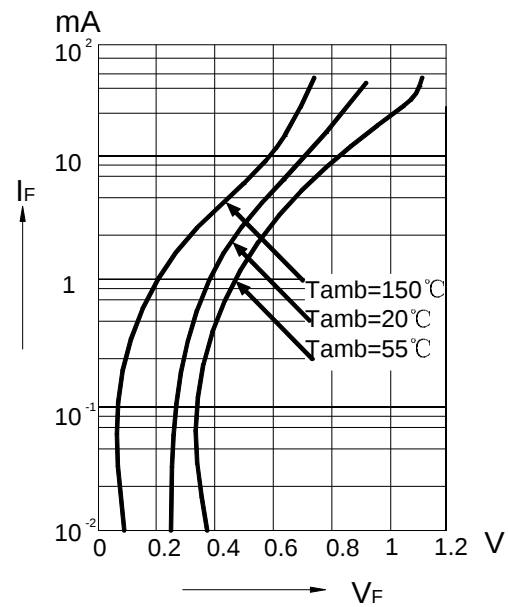


FIG.2 – FORWARD CURRENT VERSUS FORWARD VOLTAGE (TYPICAL VALUES)

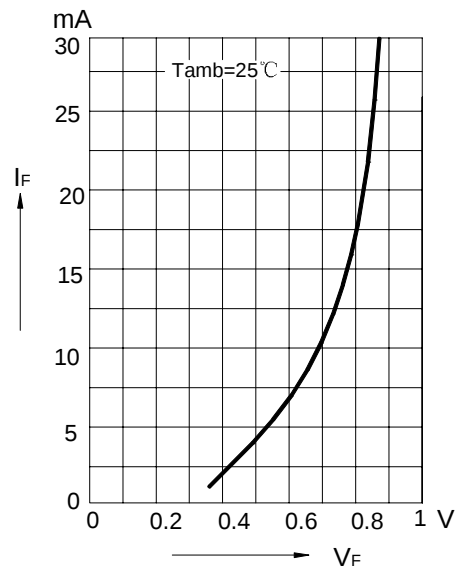


FIG.3 – REVERSE CURRENT VERSUS AMBIENT TEMPERATURE

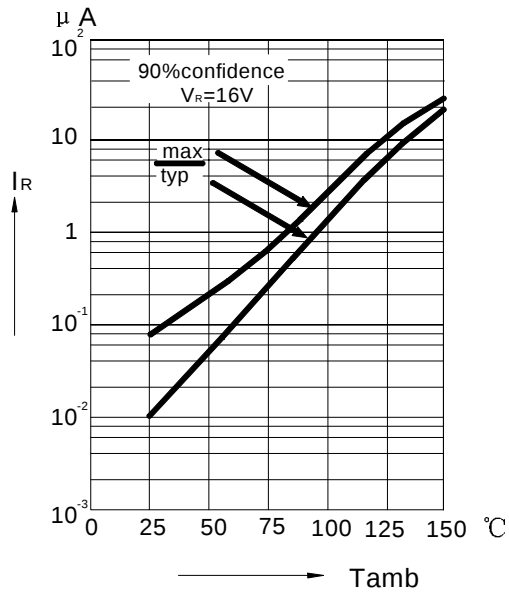


FIG.4 – REVERSE CURRENT VERSUS CONTINUOUS REVERSE VOLTAGE (TYPICAL VALUES)

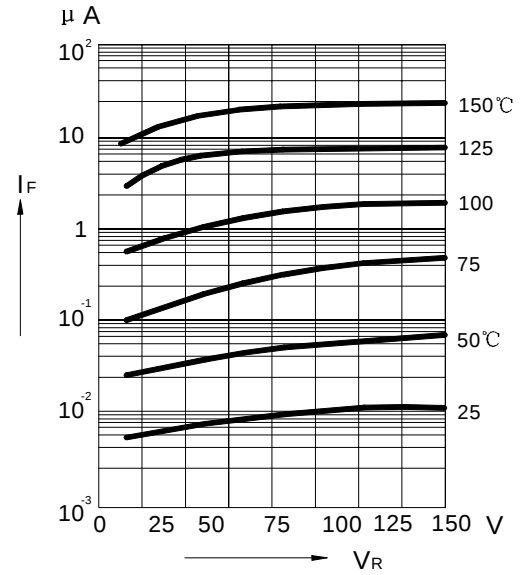


FIG.5 – CAPACITANCE CVERSUS REVERS APPLIED VOLTAGE V_R (TYPICAL VALUES)

